



MIT-019-01-F-D-A

MIT-038-01-F-D-A

MIT-057-01-L-D-A

# 0,635mm MIX TECH HEADER MIT SERIES

## SPECIFICATIONS

For complete specifications and recommended PCB layouts see [www.samtec.com?MIT](http://www.samtec.com?MIT)

**Insulator Material:**

Liquid Crystal Polymer



**Contact Material:**

Phosphor Bronze

**Plating:**

Au over 50µ" (1,27µm) Ni

**Current Rating:**

Contacts: 1.6A @ 80°C

Ground Plane: 8.7A @ 80°C

**Operating Temp Range:**

-55°C to +125°C

**Voltage Rating:**

275 VAC

**Max Cycles:**

100

**RoHS Compliant:**

Yes

**Processing:**

**Max Processing Temp:**

230°C for 60 seconds, or

260°C for 20 seconds 3x

**Lead-Free Solderable:**

Yes

**SMT Lead Coplanarity:**

(0,10mm) .004" max (019-076)

**Board Stacking:**

For applications requiring more than two connectors per board or 76 positions or higher, contact [ipg@samtec.com](mailto:ipg@samtec.com)

**Mates with:**  
MIS, MICD

Integral metal plane for power or ground

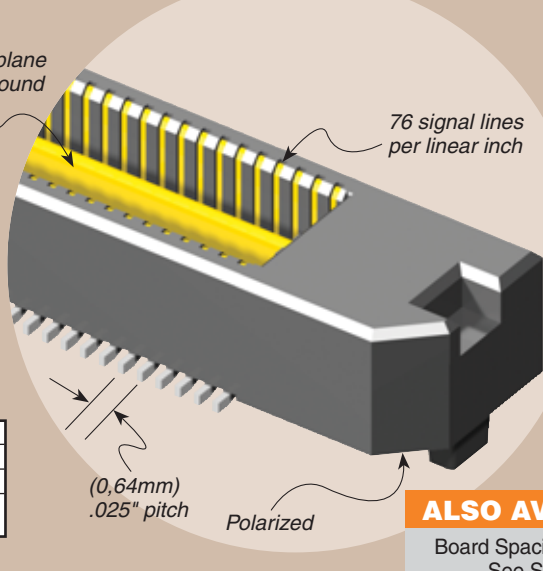
76 signal lines per linear inch

Choice of mated heights



5mm Stack Height	Rated @ -3dB Insertion Loss
Single-Ended Signaling	8.5 GHz / 17 Gbps
Differential Pair Signaling	8.5 GHz / 17 Gbps

Performance data for other stack heights available at [www.samtec.com?MIT](http://www.samtec.com?MIT)



(0,64mm)

.025" pitch

Polarized

## ALSO AVAILABLE

Board Spacing Standoffs. See SO Series.

## APPLICATION SPECIFIC OPTION

- 11mm, 16mm, 18,75mm and 22mm stack height
  - 30µ" (0,76µm) Gold
  - Differential Pair and "Partitionable" (combine differential & single-ended banks in same connector) available.
  - 95, 114 and 133 positions per row
  - Edge Mount
- Call Samtec.



-019, -038, -057, -076  
(38 total positions per bank)

Specify LEAD STYLE from chart

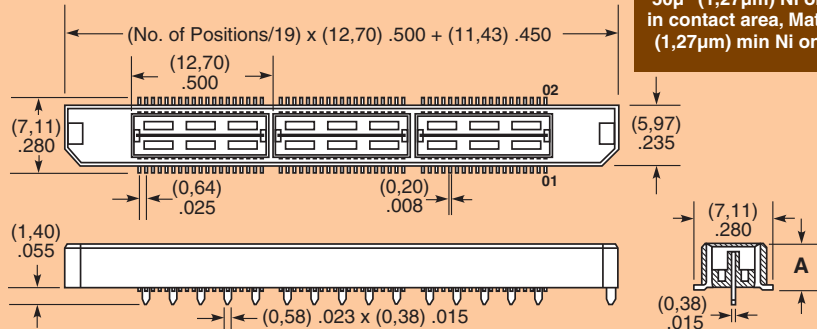
-L  
= 10µ" (0,25µm) Gold on Signal Pins and Ground Plane, Matte Tin on tails

-F  
= Gold Flash on Signal Pins and Ground Plane, Matte Tin on tails

-C\*  
= Electro-Polished Selective 50µ" (1,27µm) min Au over 150µ" (3,81µm) Ni on Signal Pins in contact area, 10µ" (0,25µm) min Au over 50µ" (1,27µm) Ni on Ground Plane in contact area, Matte Tin over 50µ" (1,27µm) min Ni on all solder tails

-K  
= (7,00mm) .275" DIA Polyimide film Pick & Place Pad

-TR  
= Tape & Reel



STACK HEIGHTS		
LEAD STYLE	A	MATED HEIGHT
-01	(4,27) .168	(5,00) .198
-02	(7,26) .286	(8,00) .315

Processing conditions will affect mated height.

**Note:** Rugged through-hole ground plane soldered to board (requires paste-over-hole, not press-fit) for added retention to PCB.

Due to technical progress, all designs, specifications and components are subject to change without notice.

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